TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

2SK2602

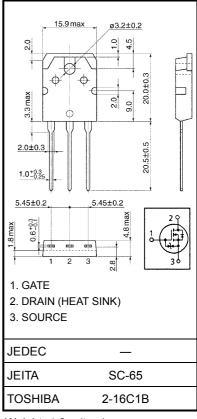
Switching Regulator Applications

Unit: mm

 $\begin{array}{ll} \bullet & Low \ drain-source \ ON \ resistance & \vdots \ R_{DS} \ (ON) = 0.9 \ \Omega \ (typ.) \\ \bullet & High \ forward \ transfer \ admittance & \vdots \ |\ Y_{fs}\ | = 5.5 \ S \ (typ.) \\ \bullet & Low \ leakage \ current & \vdots \ I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 600 \ V) \\ \bullet & Enhancement-mode & \vdots \ V_{th} = 2.0 \\ \sim 4.0 \ V \ (V_{DS} = 10 \ V, \ I_{D} = 1 \ mA) \end{array}$

Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	600	V
Drain-gate voltage (R	_{GS} = 20 kΩ)	V_{DGR}	600	V
Gate-source voltage		V_{GSS}	±30	V
Drain current	DC (Note 1)	I _D	6	Α
	Pulse (Note 1)	I _{DP}	24	Α
Drain power dissipation	n (Tc = 25°C)	P_{D}	125	W
Single pulse avalanche	e energy (Note 2)	E _{AS}	345	mJ
Avalanche current		I _{AR}	6	Α
Repetitive avalanche e	energy (Note 3)	E _{AR}	12.5	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature ra	ange	T _{stg}	-55~150	°C



Weight: 4.6 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.0	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

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Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 16.8 mH, R_G = 25 Ω , I_{AR} = 6 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.



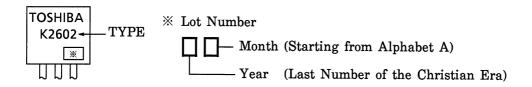
Electrical Characteristics (Ta = 25°C)

Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	I (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	600	_	_	V
Gate threshold v	voltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	٧
Drain-source O	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 3 A,	_	0.9	1.25	Ω
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 3 A	2.0	5.5	_	S
Input capacitano	e	C _{iss}			1300	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	130	_	
Output capacitance		Coss		_	400	_	
Switching time	Rise time	t _r	V_{GS}^{10V} V_{GS}^{10V} $R_{L}=100\Omega$	_	25	_	ns
	Turn-on time	t _{on}		_	45	_	
	Fall time	t _f		_	40	_	
	Turn-off time	t _{off}	$V_{DD} \stackrel{.}{=} 300V$ Duty $\leq 1\%$, $t_w = 10 \mu s$	_	150	_	
Total gate charge (gate-source plus gate-drain)		Qg			30		
Gate-source charge		Q_{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$		18	_	nC
Gate-drain ("miller") Charge		Q_{gd}			12	_	

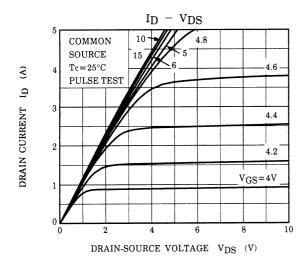
Source-Drain Ratings and Characteristics (Ta = 25°C)

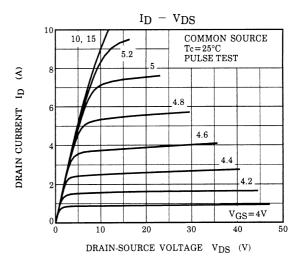
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	6	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	24	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 6 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 6 A, V _{GS} = 0 V, dI _{DR} / dt = 100 A / μs	_	1000	_	ns
Reverse recovery charge	Q _{rr}	1DR - 0 Λ, VGS - 0 V, αIDR / αt - 100 Α / μs	_	7	_	μC

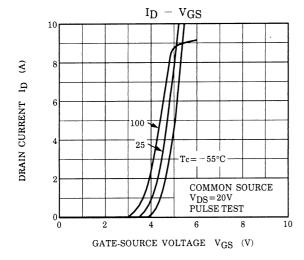
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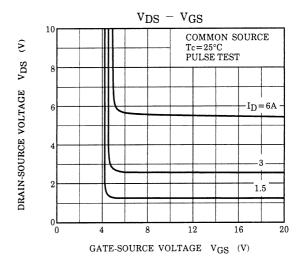


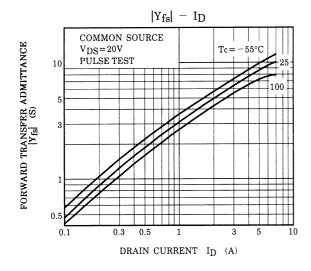
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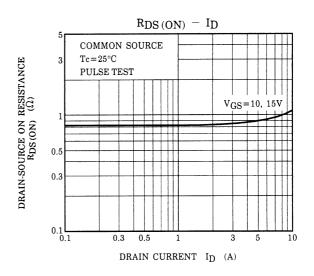




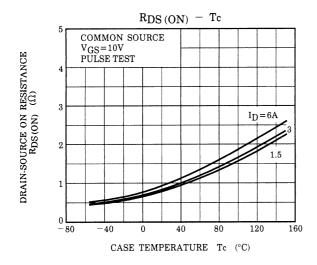


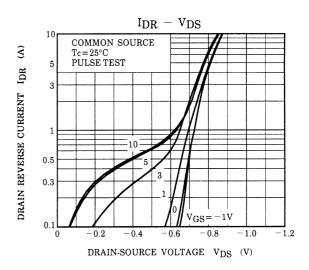


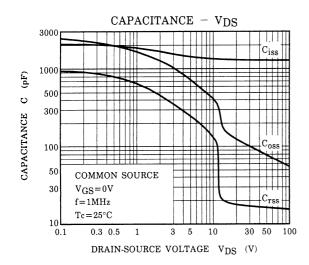


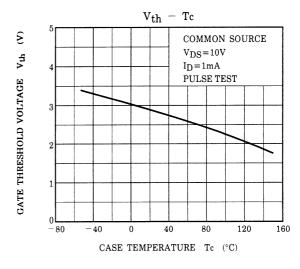


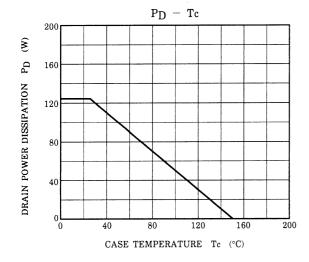
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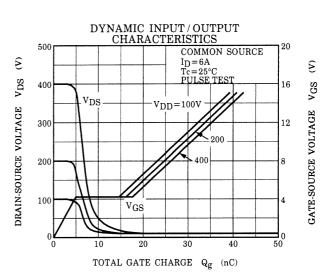




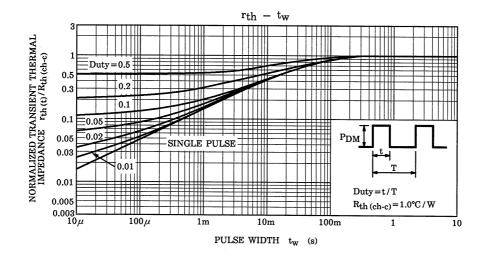


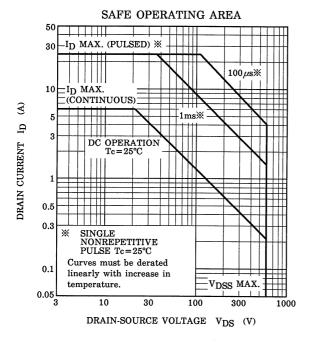


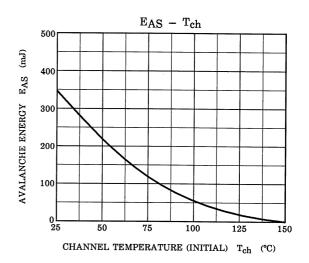


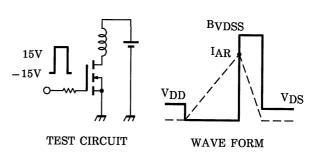


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$$R_G = 25 \Omega$$

 $V_{DD} = 90 \text{ V}, L = 16.8 \text{ mH}$ $E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD}\right)$

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